

QFSS SERIES

(0.635 mm) .025"

SHIELDED GROUND PLANE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QFSS

Insulator Material: Liquid Crystal Polymer
Contact, Ground Plane & Shield Material: Phosphor Bronze
Plating: Au over 50 μ" (1.27 μm) Ni (Tin on Ground Plane tails)
Voltage Rating: 300 VAC mated with QMSS
Operating Temp: -55 °C to +125 °C
RoHS Compliant: Yes

Board Mates: QMSS

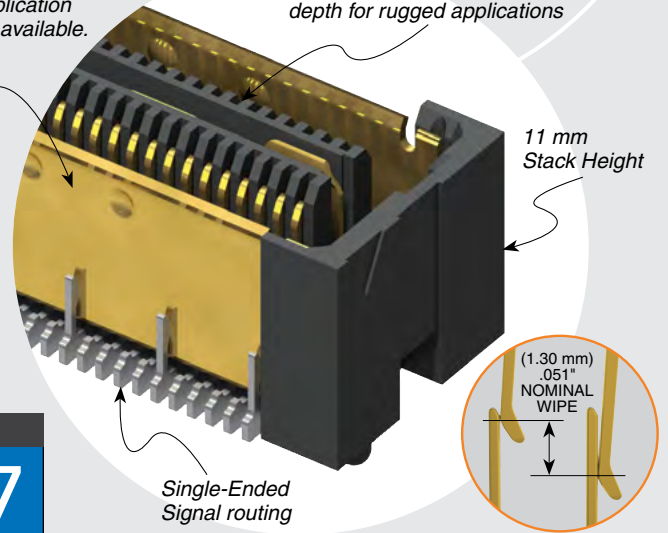
Standoffs: SO

RUGGEDIZED
BY SAMTEC

- Increased insertion depth
- Integral guide post

Standard shield grounding is GSSSSG. Application Specific options available.

Increased insertion depth for rugged applications



11 mm Stack Height

(1.30 mm) .051" NOMINAL WIPE

Single-Ended Signal routing

HIGH-SPEED CHANNEL PERFORMANCE

QMSS-DP/QFSS-DP @ 11 mm Mated Stack Height

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

17
Gbps

PROCESSING

Lead-Free Solderable: Yes
SMT Lead Coplanarity: (0.10 mm) .004" max (026-078)
Board Stacking: For applications requiring more than two connectors per board, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

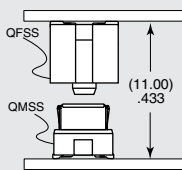


FILE NO. E111594

ALSO AVAILABLE (MOQ Required)

- Headers without Alignment Pins
- 8 Power Pins/End
- 4 or 8 Power Pins/End for (2.36 mm) .093" thick board
- Guide Holes
- 64 (-DP) and 104 pins per row Contact Samtec.

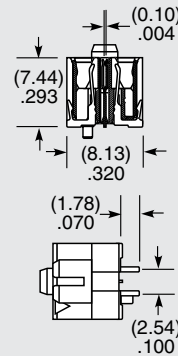
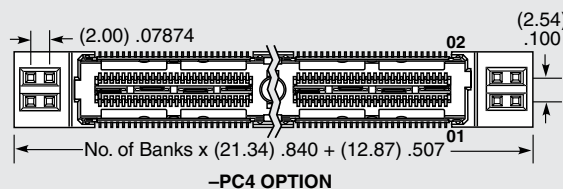
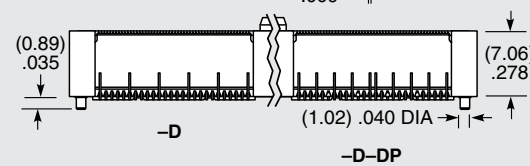
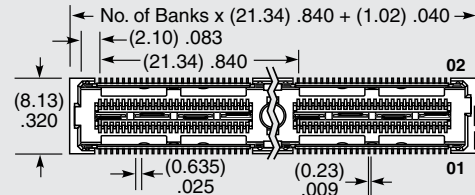
APPLICATION



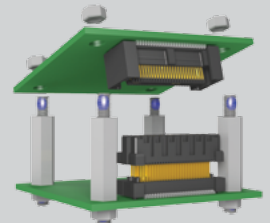
Notes: Patented

Some lengths, styles and options are non-standard, non-returnable.

QFSS	PINS PER ROW NO. OF PAIRS	04.25	PLATING OPTION	TYPE	A	OTHER OPTION
			-L = 10 μ" (0.25 μm) Gold on Signal Pins, Shield and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)	-D = Single-Ended -D-DP = Differential Pair		-PC4 = 4 Power Pins/End (N/A with -A)



OTHER SOLUTIONS



See SO Series for precision machined standoffs.